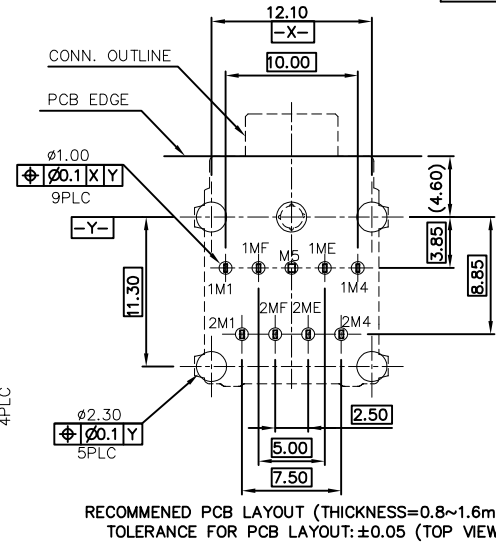
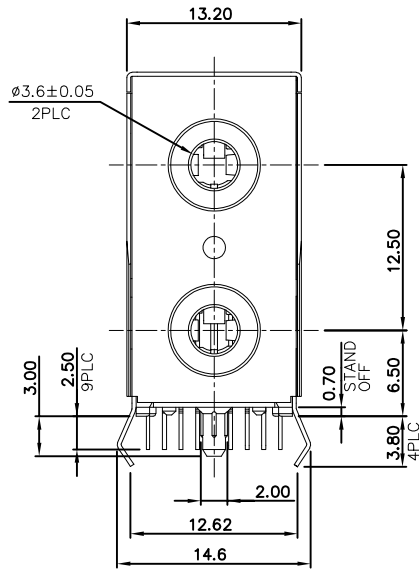
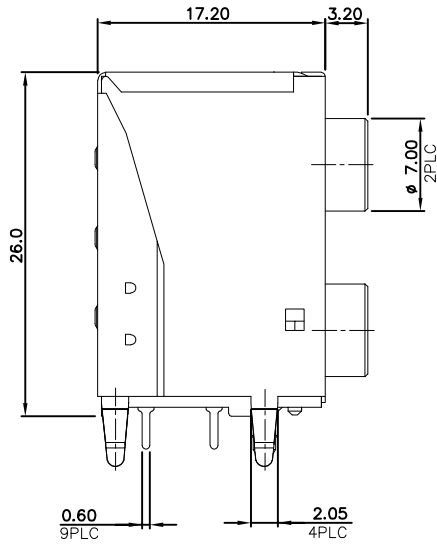


RoHS Compliant

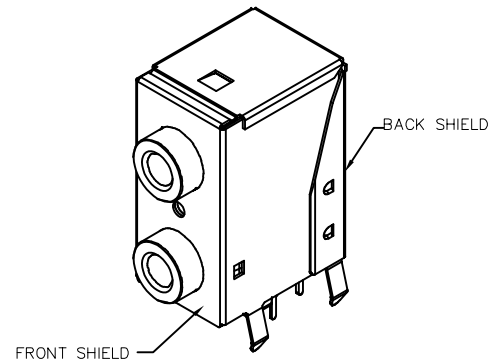
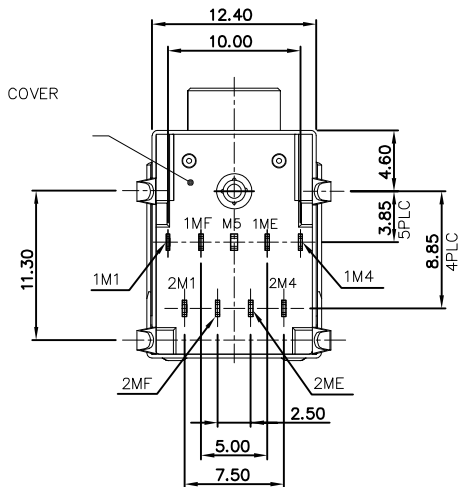
REVISIONS			
REV.	DESCRIPTION	DATE	DESIGN



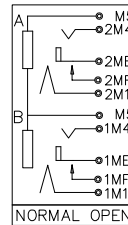
RECOMMENDED PCB LAYOUT (THICKNESS=0.8~1.6mm)
TOLERANCE FOR PCB LAYOUT: ±0.05 (TOP VIEW)

NOTES:

- MATERIAL:
 - HOUSING/COVER/RING(A,B)/INSULATOR: PA9T W/ 27%GF, UL 94V-0; COLOR: BLACK
 - RING CONTACT(PIN#1M1/2M1): PBS, t=0.25±0.05mm
 - TIP CONTACT(PIN#1M4/2M4): PBS, t=0.25±0.05mm
 - CN CONTACT(PIN#1ME/2ME): BRASS, t=0.20±0.05mm
 - CS CONTACT(PIN#1MF/2MF): PBS, t=0.20±0.05mm
 - GND CONTACT(PIN#M5): BRASS, t=0.50±0.05mm
 - BRIDGE: BRASS, t=0.30±0.05mm
 - FRONT SHIELD: SPCC, t=0.30±0.05mm
 - BACK SHIELD: SPCC, t=0.30±0.05mm
- FINISH:
 - BRIDGE/CONTACT(1M1/2M1/1M4/2M4/M5/1ME/2ME): 2.54um[100u"] MIN. BRIGHT-TIN PLATING ON OVERALL. 1.27um[50u"] MIN. NICKEL UNDERPLATED OVERALL.
 - 1MF/2MF CONTACT: GOLD FLASH AU PLATING ON CONTACT AREA. 1.27um[50u"] MIN. NICKEL UNDERPLATED OVERALL.
 - FRONT SHIELD: 1.27um[50u"] MIN. NICKEL PLATING ON OVERALL. 1.52um[60u"] MIN. COPPER UNDERPLATED OVERALL.
 - BLACK SHIELD: 2.54um[100u"] MIN. NICKEL PLATING ON OVERALL. 2.03um[80u"] MIN. COPPER UNDERPLATED OVERALL.
- WAVE SOLDER CAPABLE TO 265°C. PER TE SPEC. 109-202 CONDITION B.
- NO PIN MARK ON THE PRODUCT.
- LOW HALOGEN SPECIFICATION: CHLORINE(Cl): 900ppm MAX. BROMINE(Br): 900ppm MAX.



SCHEMATIC



Bestcreate Technology Limited

TOLERANCES UNLESS OTHERWISE SPECIFIED:

.X	± 0.30	X.*	± 5*
.XX	± 0.20	.X.*	± 3*
.XXX	± 0.10	.XX.*	± 1*

Website: www.bsc-elec.com
Email: bestcreate@bsc-elec.com

DESIGN: I. L. DATE: 2017. 3. 1

CHECKED: C. W. DATE: 2017. 3. 1

APPROVED: C. W. DATE: 2017. 3. 1

TITLE: 3.5MM PHONE JACK CONNECTOR VERTICAL 9P

MATERIAL: PART NO: PJ350-09-A001 SIZE: A4

FINISH: DWG NO: PJ350-09-A001 1 OF 2

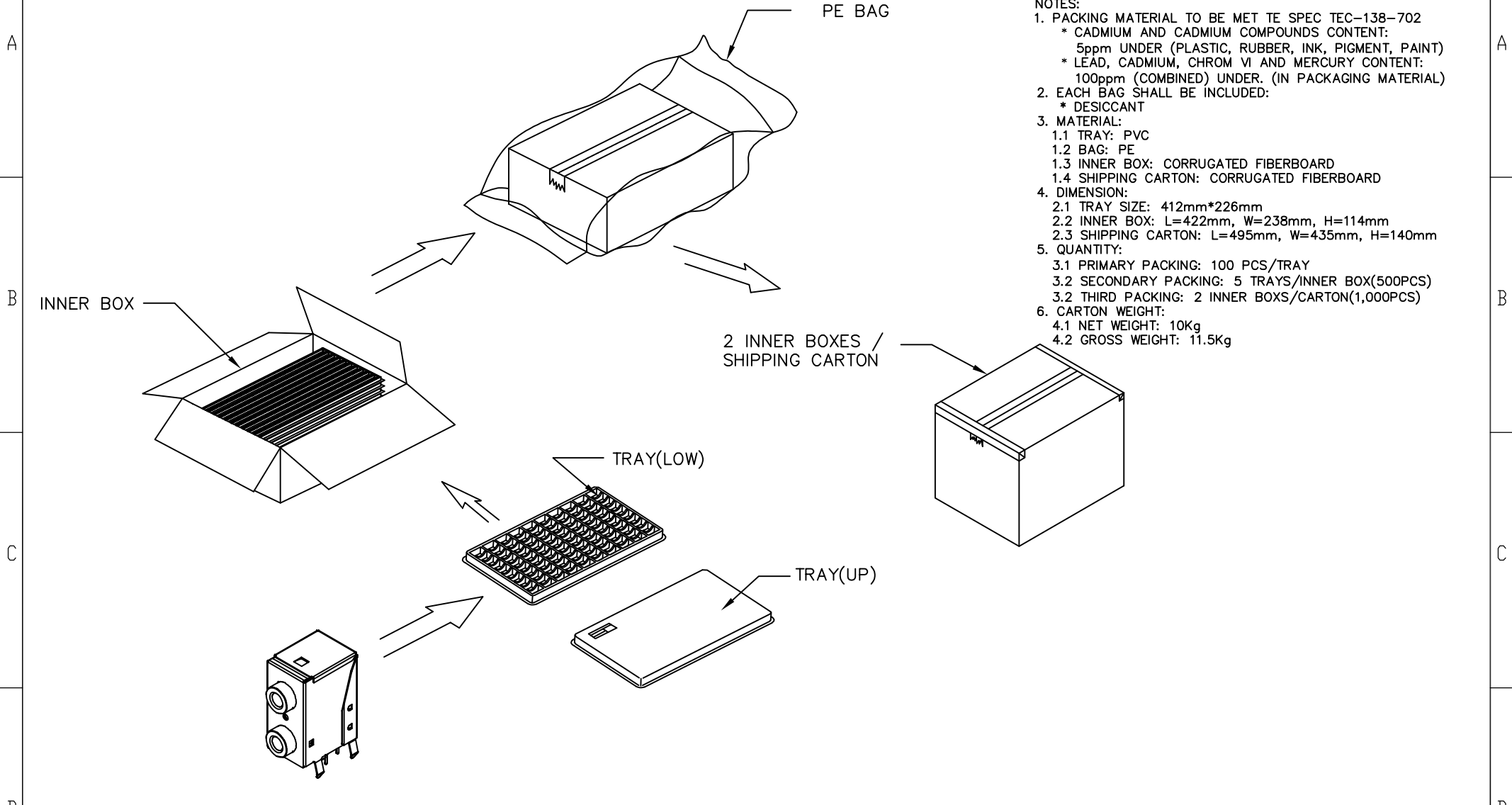
REV: A UNIT mm SCALE 1=1 QUALITY SYMBOLS

RoHS Compliant

REVISIONS			
REV.	DESCRIPTION	DATE	DESIGN

NOTES:

1. PACKING MATERIAL TO BE MET TE SPEC TEC-138-702
 - * CADMIUM AND CADMIUM COMPOUNDS CONTENT: 5ppm UNDER (PLASTIC, RUBBER, INK, PIGMENT, PAINT)
 - * LEAD, CADMIUM, CHROM VI AND MERCURY CONTENT: 100ppm (COMBINED) UNDER. (IN PACKAGING MATERIAL)
2. EACH BAG SHALL BE INCLUDED:
 - * DESICCANT
3. MATERIAL:
 - 1.1 TRAY: PVC
 - 1.2 BAG: PE
 - 1.3 INNER BOX: CORRUGATED FIBERBOARD
 - 1.4 SHIPPING CARTON: CORRUGATED FIBERBOARD
4. DIMENSION:
 - 2.1 TRAY SIZE: 412mm*226mm
 - 2.2 INNER BOX: L=422mm, W=238mm, H=114mm
 - 2.3 SHIPPING CARTON: L=495mm, W=435mm, H=140mm
5. QUANTITY:
 - 3.1 PRIMARY PACKING: 100 PCS/TRAY
 - 3.2 SECONDARY PACKING: 5 TRAYS/INNER BOX(500PCS)
 - 3.2 THIRD PACKING: 2 INNER BOXS/CARTON(1,000PCS)
6. CARTON WEIGHT:
 - 4.1 NET WEIGHT: 10Kg
 - 4.2 GROSS WEIGHT: 11.5Kg



Bestcreate Technology Limited

TOLERANCES UNLESS OTHERWISE SPECIFIED:

.X	±	0.30	X.*	±	5°
.XX	±	0.20	.X*	±	3°
.XXX	±	0.10	.XX*	±	1°

Website: www.bsc-elec.com
 Email: bestcreate@bsc-elec.com

DESIGN: I.L
 DATE: 2017.3.1
 CHECKED: C.W
 DATE: 2017.3.1
 APPROVED: C.W
 DATE: 2017.3.1

TITLE: 3.5MM PHONE JACK CONNECTOR VERTICAL 9P
 MATERILA: P.J350-09-A001
 PART NO: P.J350-09-A001
 SIZE: A4
 FINSH: P.J350-09-A001
 DWG NO: P.J350-09-A001
 2 OF 2

REV: A
 UNIT: mm
 SCALE: 1=1
 QUALITY SYMBOLS: